

Spec. No.: RMPC-K-HTS-0001 /2
Date: 2017.1.10

Specification

Title: FIXED THICK FILM CHIP RESISTORS;
RECTANGULAR TYPE AND Pb<100ppm

Style: RMPC04,06,10,16,20,32,35

RoHS COMPLIANCE ITEM
Halogen and Antimony Free

Product specification contained in this specification
are subject to change at any time without notice
If you have any questions or a Purchasing Specification for any quality
Agreement is necessary, please contact our sales staff.



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Note: Stock conditions

Temperature: +5°C ~ +35°C

Relative humidity: 25% ~ 75%

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

1. Scope

1.1 This specification covers the detail requirements for fixed thick film chip resistors; rectangular type, style of RMPC04, 06, 10, 16, 20, 32, 35.

1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014
IEC60115-1: 2008, IEC60115-8: 2009, IEC60115-8-1: 2014
EIAJ RC-2134C-2010

2. Classification

Type designation shall be the following form.

(Example)


1)	RMPC	16	-	123	J	TP
	1	2	3	4	5	6
	Style					
2)	RMPC	16		JP		TP
	1	2		4		6
	Style					

1 Fixed thick film chip resistors; rectangular type & Pb<100ppm

2 Dimension

3 Temperature coefficient of resistance

-(Dash)	Standard
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 Style

4 Rated resistance

123	E24 Series, 3 digit, Ex. 123--> 12kΩ,
1000	E96 Series, 4 digit, Ex. 1000-->100Ω 1022--> 10.2kΩ
JP	Chip jumper

5 Tolerance on rated resistance

F	±1%
J	±5%

6 Packaging form

B	Bulk (loose package)
PA	Press pocket taping
TH	Paper taping
TP	
TE	Embossed taping

3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1(1)

Style	Rated dissipation (W)	Temperature coefficient of resistance (10 ⁻⁶ /°C)	Rated resistance range (Ω)	Preferred number series for resistors	Tolerance on rated resistance	
RMPC04	0.03	Standard	±200	100~1M	E24, E96	F(±1%)
			+600~0	10~97.6k		
			±200	10k~1M	E24	J(±5%)
			+600~0	10~9.1k		
RMPC06	0.05	Standard	±200	100~1M	E24, 96	F(±1%)
			+600~0	10~97.6		
			+800~-100	1~9.76	E24	J(±5%)
			±200	100~10M		
			+600~0	10~91		
			+800~-100	1~9.1		
RMPC10	0.063	Standard	±200	100~1M	E24, 96	F(±1%)
			+500~-200	10~97.6		
			+800~-100	1~9.76	E24	J(±5%)
			±200	100~10M		
			+600~0	10~91		
			+800~-100	1~9.1		
RMPC16	0.1	Standard	±200	100~1M	E24, 96	F(±1%)
			+500~-200	10~97.6		
			+800~-100	1~9.76	E24	J(±5%)
			±200	100~10M		
			+600~0	10~91		
			+800~-100	1~9.1		
RMPC20	0.125	Standard	±200	100~1M	E24, 96	F(±1%)
			+500~-200	10~97.6		
			+800~-100	1~9.76	E24	J(±5%)
			±200	100~10M		
			+600~0	10~91		
			+800~-100	1~9.1		
RMPC32	0.25	Standard	±200	100~1M	E24, 96	F(±1%)
			+500~-200	10~97.6		
			+800~-100	1~9.76	E24	J(±5%)
			±200	100~10M		
			+600~0	10~91		
			+800~-100	1~9.1		
RMPC35	0.33	Standard	±200	100~1M	E24, 96	F(±1%)
			+500~-200	10~97.6		
			+800~-100	1~9.76	E24	J(±5%)
			±200	100~10M		
			+600~0	10~91		
			+800~-100	1~9.1		

Table-1(2)

Style	Limiting element voltage (V)	Isolation voltage (V)	Category temperature range (°C)
RMPC04	15	50	-55~+125
RMPC06	25		
RMPC10	100	100	
RMPC16			
RMPC20	150	500	
RMPC32			
RMPC35			

Note. Rated current of chip jumper: RMPC04: 0.5(A), RMPC06,10: 1(A), RMPC16,20,32,35: 2(A)

Note. Resistance value of chip jumper: 50 mΩ max.

3.2 Climatic category

55/125/56	Lower category temperature	-55 °C
	Upper category temperature	+125 °C
	Duration of the damp heat, steady state test	56days

3.3 Stability class

5%	Limits for change of resistance:	
	-for long-term tests	±(5%+0.1Ω) Chip jumper: 50 mΩ max.
	-for short-term tests	±(1%+0.05Ω) Chip jumper: 50 mΩ max.

3.4 Derating

The derated values of dissipation (or current rating in case of chip jumper) at temperature in excess of 70 °C shall be as indicated by the following curve.

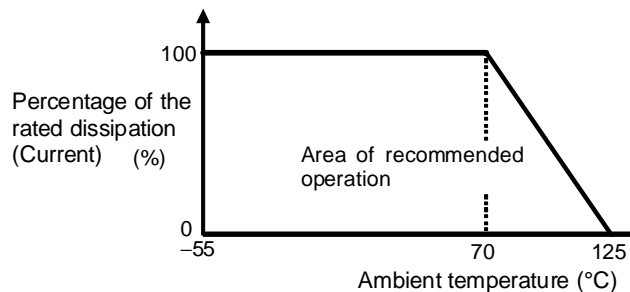


Figure-1 Derating curve

3.5 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{P \cdot R}$$

E : Rated voltage (V)
 P : Rated dissipation (W)
 R : Rated resistance (Ω)

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
B	Bulk (loose package)		1,000 pcs.	RMPC04,06,10,16,20,32,35
PA	Press pocket taping (paper taping)	8mm width, 2mm pitches	20,000 pcs.	RMPC04
			15,000 pcs.	RMPC06
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	RMPC10
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RMPC16,20,32
TE	Embossed taping	8mm width, 4mm pitches	4,000 pcs.	RMPC35

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

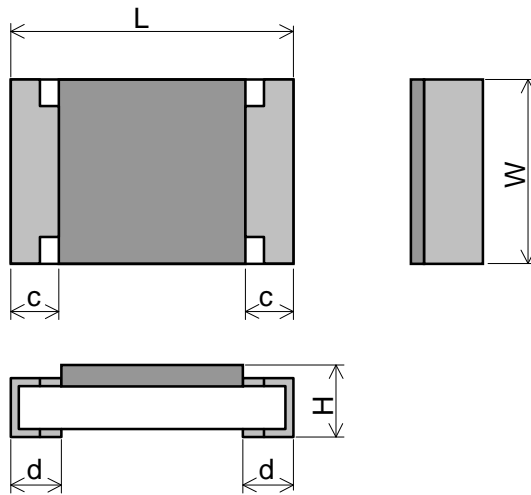


Figure-2

Table-3

Unit : mm

Style	L	W	H	c	d
RMPC04	0.4±0.02	0.2±0.02	0.13±0.02	0.08±0.03	0.1±0.03
RMPC06	0.6±0.03	0.3±0.03	0.23±0.03	0.1±0.05	0.15±0.05
RMPC10	1.0±0.05	0.5±0.05	0.35±0.05	0.2±0.1	0.25 ^{+0.05} _{-0.10}
RMPC16	1.6±0.1	0.8 ^{+0.15} _{-0.05}	0.45±0.10	0.3±0.1	0.3±0.1
RMPC20	2.0±0.1	1.25±0.10	0.55±0.10	0.4±0.2	0.4±0.2
RMPC32	3.1±0.1	1.6±0.15	0.55±0.10	0.5±0.25	0.5±0.25
RMPC35	3.1±0.15	2.5±0.15	0.55±0.15	0.5±0.25	0.5±0.25

5.2 Net weight (Reference)

Style	Net weight(mg)
RMPC04	0.035
RMPC06	0.16
RMPC10	0.6
RMPC16	2
RMPC20	5
RMPC32	9
RMPC35	16

Table-4(2)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
5	Mounting Overload (in the mounted state) Solvent resistance of the marking	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.13 The applied voltage shall be 2.5 times the rated voltage or twice the limiting element voltage, whichever is the less severe. Duration: 2 s Visual examination Resistance Sub-clause 4.30 Solvent: 2-propanol Solvent temperature: 23 °C ± 5 °C Method 1 Rubbing material: cotton wool Without recovery	No visible damage $\Delta R \leq \pm (1\%+0.05\Omega)$ Chip jumper: 50m Ω max. Legible marking
6	Mounting Bound strength of the end face plating Final measurements	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.33 Bent value: 3 mm Resistance Sub-clause 4.33.6 Visual examination	$\Delta R \leq \pm (1\%+0.05\Omega)$ Chip jumper: 50m Ω max. No visible damage
7	Resistance to soldering heat Component solvent resistance	Sub-clause 4.18 Solder temperature: 260 °C ± 5 °C Immersion time: 10 s ± 0.5 s Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C ± 5 °C Method 2 Recovery: 48 h Visual examination Resistance	As in 4.18.3.4 No sign of damage such as cracks. $\Delta R \leq \pm (1\%+0.05\Omega)$ Chip jumper: 50m Ω max. No visible damage $\Delta R \leq \pm (1\%+0.05\Omega)$ Chip jumper: 50m Ω max.

Table-4(3)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
8	Mounting Adhesion Rapid change temperature	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.32 Force: 3N (RMPC04: 2N, RMPC06: 3N) Duration: 10 s ± 1 s Visual examination Sub-clause 4.19 Lower category temperature: -55 °C Upper category temperature: +125 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination Resistance	No visible damage No visible damage $\Delta R \leq \pm(1\%+0.05\Omega)$ Chip jumper: 50m Ω max.
9	Climatic sequence -Dry heat -Damp heat, cycle (12+12hour cycle) First cycle -Cold -Damp heat, cycle (12+12hour cycle) Remaining cycle -D.C. load	Sub-clause 4.23 Sub-clause 4.23.2 Test temperature: +125 °C Duration: 16 h Sub-clause 4.23.3 Test method: 2 Test temperature: 55 °C [Severity(2)] Sub-clause 4.23.4 Test temperature -55 °C Duration: 2h Sub-clause 4.23.6 Test method: 2 Test temperature: 55 °C [Severity (2)] Number of cycles: 5 cycles Sub-clause 4.23.7 The applied voltage shall be the rated voltage or the limiting element voltage whichever is the smaller. Duration: 1 min. Visual examination Resistance	No visible damage $\Delta R \leq \pm(5\%+0.1\Omega)$ Chip jumper: 50m Ω max.

Table-4(4)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
10	Mounting Endurance at 70 °C	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.25.1 Ambient temperature: 70 °C ± 2 °C Duration: 1000 h The voltage shall be applied in cycles of 1.5 h on and 0.5 h. The applied voltage shall be the rated voltage or the limiting element voltage whichever is the smaller. Examination at 48 h , 500 h and 1000 h: Visual examination Resistance	No visible damage $\Delta R \leq \pm (5\%+0.1\Omega)$ Chip jumper: 50mΩ max.
11	Mounting Variation of resistance with temperature	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.8 -55 °C / +20 °C +20 °C / +125°C	As in Table-1
12	Mounting Damp heat, steady state	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.24 Ambient temperature: 40 °C ± 2 °C Relative humidity : 93 \pm ₃ % a) 1st group: without voltage applied. b) 2nd group: The d. c. voltage shall be applied continuously. The voltage shall be accordance with Sub-clause 4.24.2.1 b). without polarizing voltage [4.24.2.1, c)] Visual examination Resistance	No visible damage Legible marking $\Delta R \leq \pm (5\%+0.1\Omega)$ Chip jumper: 50mΩ max.
13	Dimensions (detail) Mounting Endurance at upper category temperature	Sub-clause 4.4.3 Sub-clause 4.31 Substrate material: Epoxide woven glass TSub-clause 4.25.3 Ambient temperature:125 °C ± 2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	As in Table-3 No visible damage $\Delta R \leq \pm (5\%+0.1\Omega)$ Chip jumper: 50mΩ max.

- RMPC10,16,20,32,35

· RMPC04,06

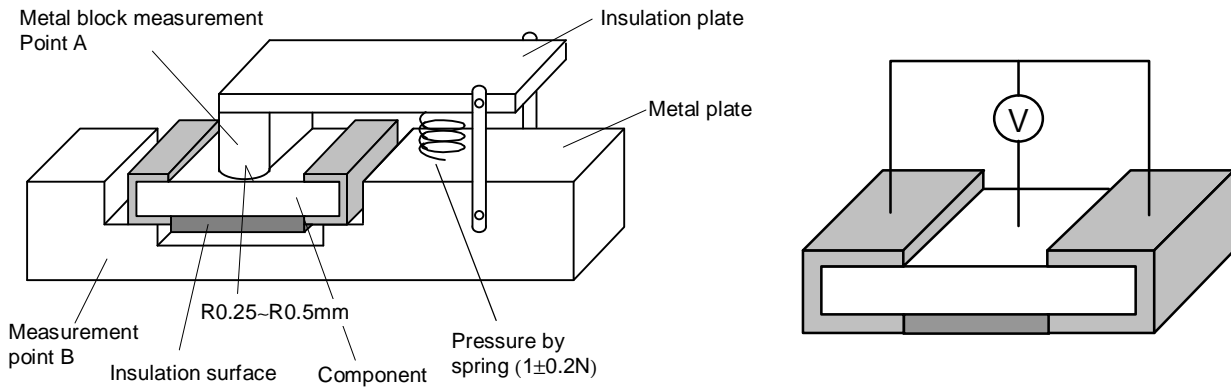


Figure-3

8. Taping

8.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010

8.2 Taping dimensions

8.2.1 Press pocket taping (Paper taping, 8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-5.

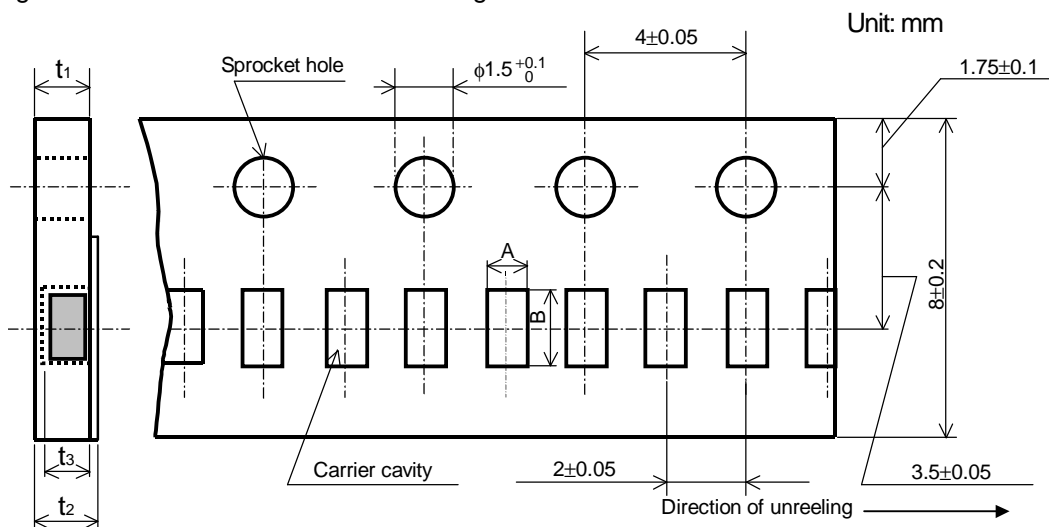


Figure-4

Table-5

Unit: mm

Style	A	B	t ₁	t ₂	t ₃
RMPC04	0.24±0.03	0.45±0.03	0.31±0.03	0.36±0.03	0.15±0.02
RMPC06	0.37±0.05	0.67±0.05	0.42±0.03	0.45±0.05	0.27±0.02

8.2.2 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-5 and Table-6.

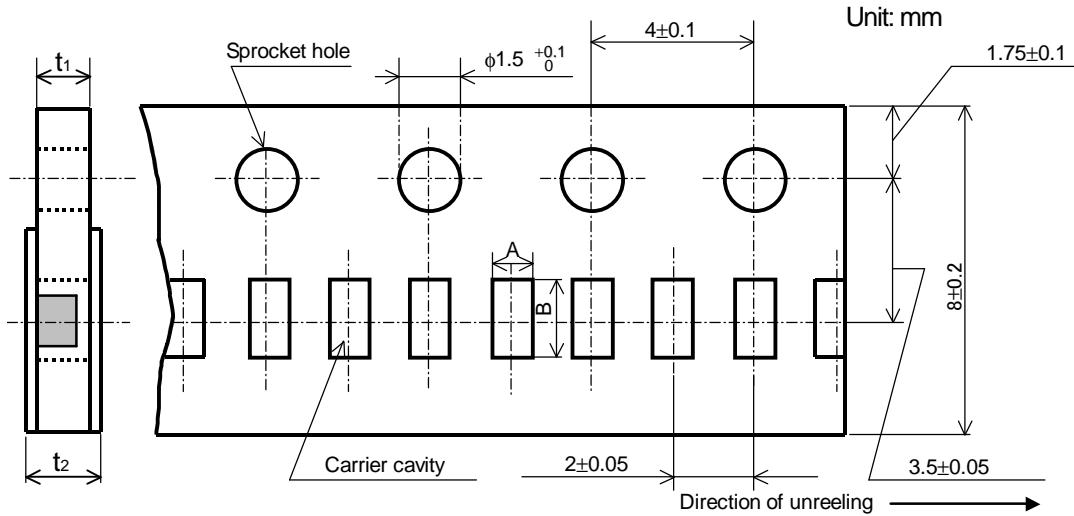


Figure-5

Table-6

Unit: mm

Style	A	B	t_1	t_2
RMPC10	$0.65^{+0.05}_{-0.10}$	$1.15^{+0.05}_{-0.10}$	0.4 ± 0.05	0.5max.

8.2.3 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-7.

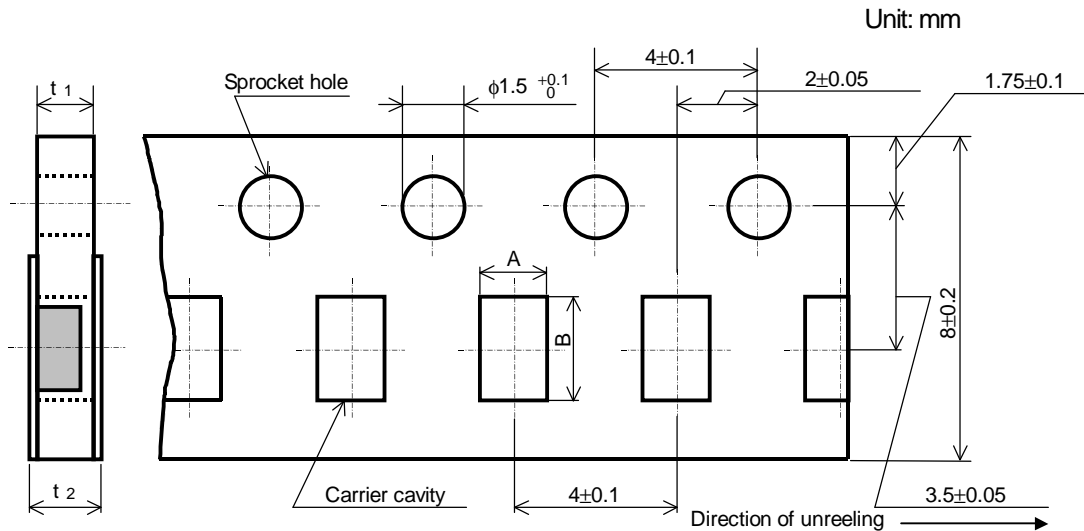


Figure-6

Table-7

Unit: mm

Style	A	B	t_1	t_2
RMPC16	1.15 ± 0.15	1.9 ± 0.2	0.6 ± 0.1	0.8max.
RMPC20	1.65 ± 0.15	2.5 ± 0.2	0.8 ± 0.1	1.0max.
RMPC32	2.00 ± 0.15	3.6 ± 0.2		

8.2.4 Embossed tapping dimensions shall be in accordance with Figure-7 and Table-8.

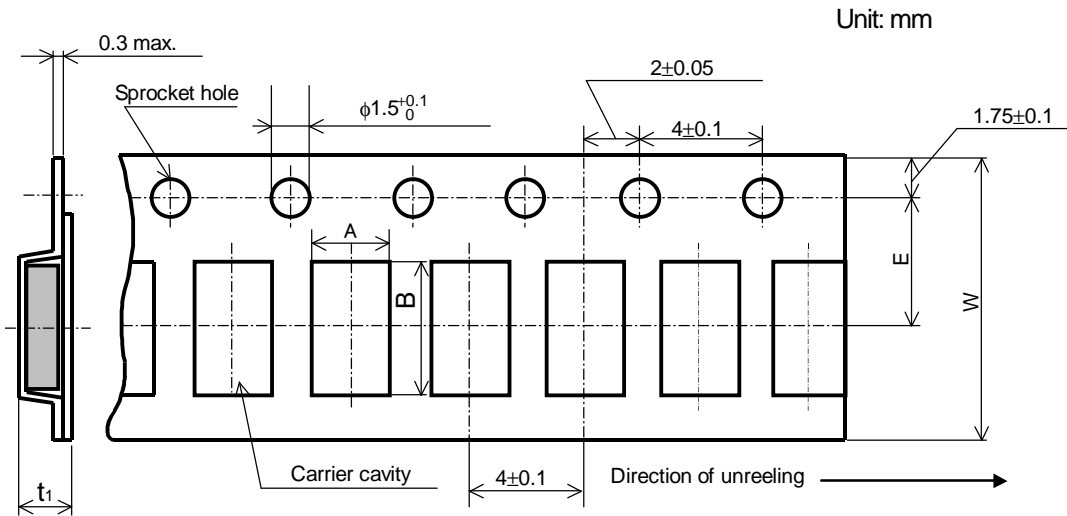


Figure-7

Table-8

Style	A	B	W	E	t ₁
RMPC35	2.85±0.20	3.5±0.2	8.0±0.2	3.5±0.05	1.0±0.2

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ± 0.2 mm.
- 5). The peel strength of the top cover tape shall be within 0.1N to 0.5N on the test method as shown in the following RMPC04,06: Figure-8, RMPC10,16,20,32: Figure-9, RMPC35: Figure-10.
- 6). When the tape is bent with the minimum radius for 25 mm the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.
The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.

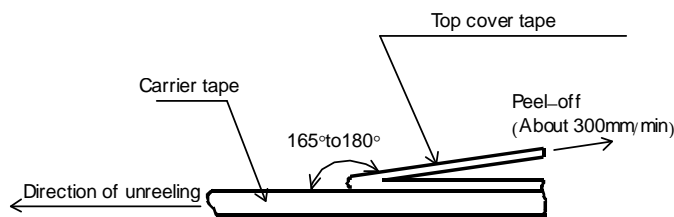


Figure-8

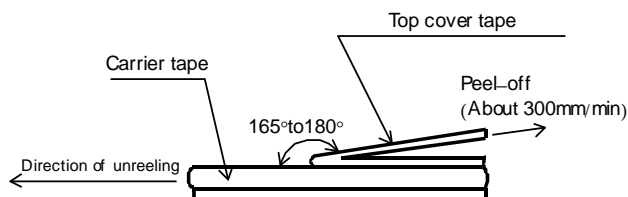


Figure-9

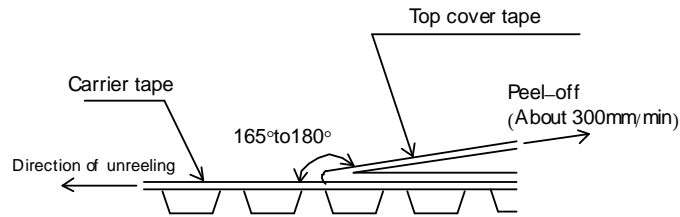


Figure-10

8.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-11 and Table-9.

Plastic reel (Based on EIAJ ET-7200C)

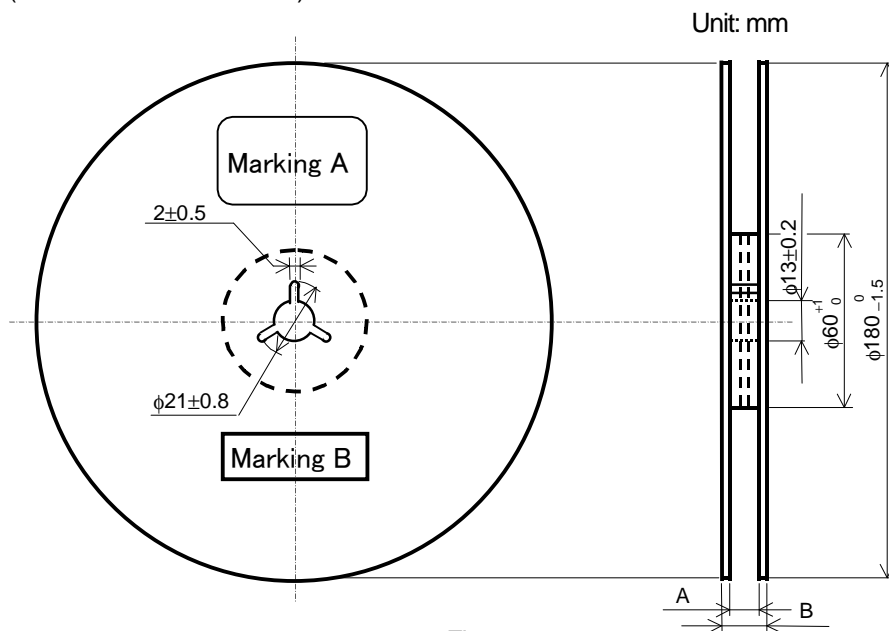


Figure-11

Table-9

Style	A	B	Note
RMPC04,06,10,16,20,32,35	9 ^{+1.0} ₀	11.4±1.0	Injection molding
		13±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

8.4 Leader and trailer tape.

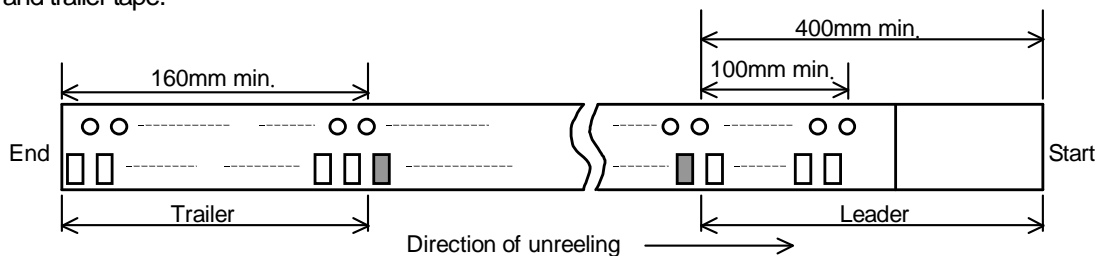


Figure-12

9. Marking on package

The label of a minimum package shall be legibly marked with follows.

9.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others

9.2 Marking B (KAMAYA Control label)